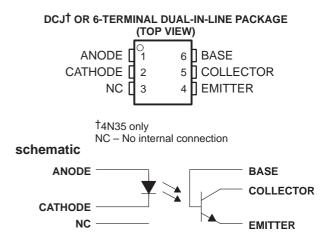
#### COMPATIBLE WITH STANDARD TTL INTEGRATED CIRCUITS

- Gallium-Arsenide-Diode Infrared Source Optically Coupled to a Silicon npn Phototransistor
- High Direct-Current Transfer Ratio
- High-Voltage Electrical Isolation
   1.5-kV, 2.5-kV, or 3.55-kV Rating
- High-Speed Switching
   t<sub>r</sub> = 7 μs, t<sub>f</sub> = 7 μs Typical
- Typical Applications Include Remote Terminal Isolation, SCR and Triac Triggers, Mechanical Relays and Pulse Transformers
- Safety Regulatory Approval UL/CUL, File No. E65085



## absolute maximum ratings at 25°C free-air temperature (unless otherwise noted)†

Input-to-output peak voltage (8-ms half sine wave):	4N35 3.55 kV
	4N36
	4N37 1.5 kV
Input-to-output root-mean-square voltage (8-ms half	sine wave): 4N35 2.5 kV
	4N36 1.75 kV
	4N37 1.05 kV
Collector-base voltage	
Collector-emitter voltage (see Note 1)	30 V
Emitter-base voltage	
Input-diode reverse voltage	6 V
	60 mA
	3 A
	100 mA
Continuous total power dissipation at (or below) 25°c	C free-air temperature:
Infrared-emitting diode (see Note 2)	100 mW
	300 mW
Continuous power dissipation at (or below) 25°C lea	d temperature:
Infrared-emitting diode (see Note 4)	100 mW
	500 mW
	–55°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for	
, ,	

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these conditions is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. This value applies when the base-emitter diode is open-circulated.
  - 2. Derate linearly to 100°C free-air temperature at the rate of 1.33 mW/°C.
  - 3. Derate linearly to 100°C free-air temperature at the rate of 4 mW/°C.
  - 4. Derate linearly to 100°C lead temperature at the rate of 1.33 mW/°C. Lead temperature is measured on the collector lead 0.8 mm (1/32 inch) from the case.
  - 5. Derate linearly to 100°C lead temperature at the rate of 6.7 mW/°C.



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## electrical characteristics at 25°C free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT	
V(BR)CBO	Collector-base breakdown voltage	$I_C = 100 \mu\text{A},  I_E = 0, \qquad \qquad I_F = 0$	70†			V	
V <sub>(BR)</sub> CEO	Collector-emitter breakdown voltage	$I_C = 10 \text{ mA},  I_B = 0,  I_F = 0$	30†			V	
V <sub>(BR)EBO</sub>	Emitter-base breakdown voltage	$I_E = 100 \mu\text{A},  I_C = 0, \qquad \qquad I_F = 0$	7†			V	
IR	Input diode static reverse current	V <sub>R</sub> = 6 V			10†	μΑ	
IIO	Input-to-output current	V <sub>IO</sub> = rated peak value, t = 8 ms			100	mA	
		$V_{CE} = 10 \text{ V},  I_F = 10 \text{ mA},  I_B = 0$	10†				
IC(on)	On-state collector current	$V_{CE} = 10 \text{ V},  I_F = 10 \text{ mA},  I_B = 0, \\ T_A = -55^{\circ}C$	4†			mA	
		$V_{CE} = 10 \text{ V},  I_F = 10 \text{ mA},  I_B = 0, \\ T_A = 100^{\circ}\text{C}$	4†				
		V <sub>CE</sub> = 10 V, I <sub>F</sub> = 0 I <sub>B</sub> = 0		1	50	nA	
<sup>I</sup> C(off)	Off-state collector current	$V_{CE} = 30 \text{ V},  I_{F} = 0, \qquad I_{B} = 0, \\ T_{A} = 100^{\circ}\text{C}$			500†	μΑ	
hFE	Transistor static forward current transfer ratio	$V_{CE} = 5 \text{ V}, \qquad I_{C} = 10 \text{ mA}, \qquad I_{F} = 0$		500			
VF		I <sub>F</sub> = 10 mA	0.8†		1.5		
	Input diode static forward voltage	$I_F = 10 \text{ mA},  T_A = -55^{\circ}\text{C}$	0.9†		1.7	V	
		I <sub>F</sub> = 10 mA, T <sub>A</sub> = 100°C	0.7†		1.4		
VCE(sat)	Collector-emitter saturation voltage	$I_C = 0.5 \text{ mA},  I_F = 10 \text{ mA},  I_B = 0 \text{ mA}$			0.3†	V	
rIO	Input-to-output internal resistance	V <sub>IO</sub> = 500 V, See Note 6	1011†			Ω	
C <sub>io</sub>	Input-to-output capacitance	$V_{IO} = 0$ , $f = 1 \text{ MHz}$ , See Note 6		1	2.5†	pF	

† JEDEC registered data
NOTE 6: These parameters are measured between both input-diode leads shorted together and all the phototransistor leads shorted together.

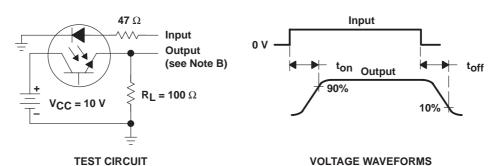
## switching characteristics at 25°C free-air temperature†

	PARAMETER	र		TEST	CONDITIONS	MIN	TYP	MAX	UNIT
ton	Time-on time			$V_{CC} = 10 \text{ V},$	$I_{C(on)} = 2 \text{ mA},$		7	10	
toff	Turn-off time			$R_L = 100 \Omega$ ,	See Figure 1		7	10	μs

<sup>†</sup> JEDEC registered data



#### PARAMETER MEASUREMENT INFORMATION



- NOTES: A. The input waveform is supplied by a generator with the following characteristics:  $Z_O = 50 \Omega$ ,  $t_\Gamma \le 15$  ns, duty cycle  $\approx 1\%$ ,  $t_W = 100 \ \mu s$ .
  - B. The output waveform is monitored on an oscilloscope with the following characteristics:  $t_r \le 12$  ns,  $R_{in} \ge 1$  M $\Omega$ ,  $C_{in} \le 20$  pF.

Figure 1. Switching Times

## TYPICAL CHARACTERISTICS

## **OFF-STATE COLLECTOR CURRENT** vs FREE-AIR TEMPERATURE 10,000 V<sub>CE</sub> = 10 V 4,000 IC(off) - Off-State Collector Current - nA $I_B = 0$ IF = 0 1,000 400 100 40 10 1 0.4 0.1 10 50 90 100 T<sub>A</sub> – Free-Air Temperature – °C Figure 2

## TRANSISTOR STATIC FORWARD **CURRENT TRANSFER RATIO (NORMALIZED)** vs

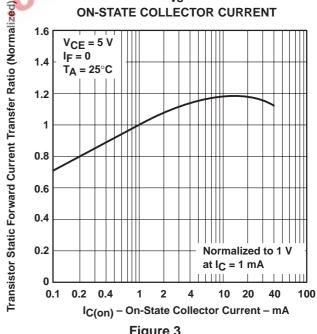


Figure 3

#### TYPICAL CHARACTERISTICS

#### **COLLECTOR CURRENT** vs **MODULATION FREQUENCY** 10 V<sub>CC</sub> = 10 V 4 $I_B = 0$ T<sub>A</sub> = 25°C $R_L = 100 \Omega$ I<sub>C</sub> – Collector Current – mA 2 1 $R_L = 1 \Omega$ 0.4 0.2 0.1 $R_L = 475 \Omega$ 0.04 0.02 0.01 100 400 1000 10 40 f<sub>mod</sub> – Modulation Frequency – kHz

Figure 4

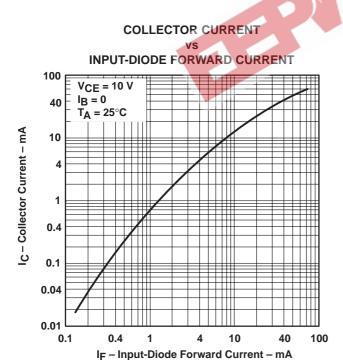


Figure 6

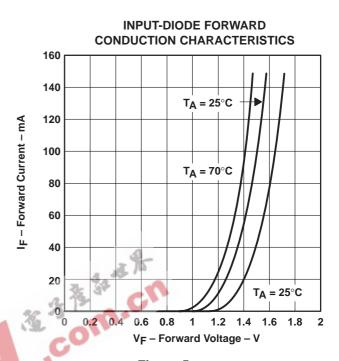
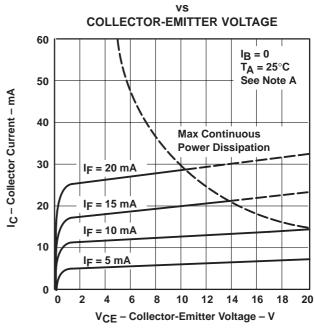


Figure 5

**COLLECTOR CURRENT** 



NOTE A. Pulse operation of input diode is required for operation beyond limits shown by dotted lines.

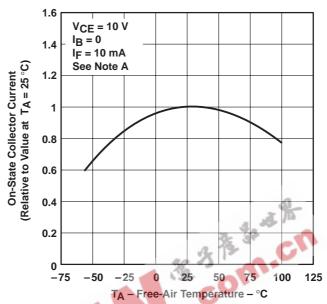
Figure 7



## **TYPICAL CHARACTERISTICS**

# ON-STATE COLLECTOR CURRENT (RELATIVE TO VALUE AT 25°C)

## FREE-AIR TEMPERATURE



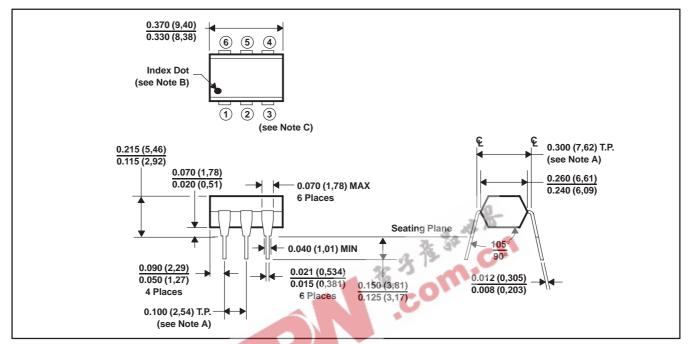
NOTE A. These parameters were measured using pulse techniques,  $t_W$  = 1 ms, duty cycle  $\leq$  2 %.

Figure 8



#### **APPLICATION INFORMATION**

The devices consist of a gallium-arsenide infrared-emitting diode and an npn silicon phototransistor. Each device is available in a 6-terminal plastic dual-in-line package, shown in Figure 9, or in a DCJ plastic dual surface-mount optocoupler package (see Mechanical Data).



NOTES: A. Terminals are within 0.005 (0,13) radius of true position (T.P.) with maximum material condition and unit installed.

- B. Terminal 1 identified by index dot.
- C. The dimensions given fall within JEDEC MO-001 AM dimensions.
- D. All linear dimensions are in inches (millimeters).

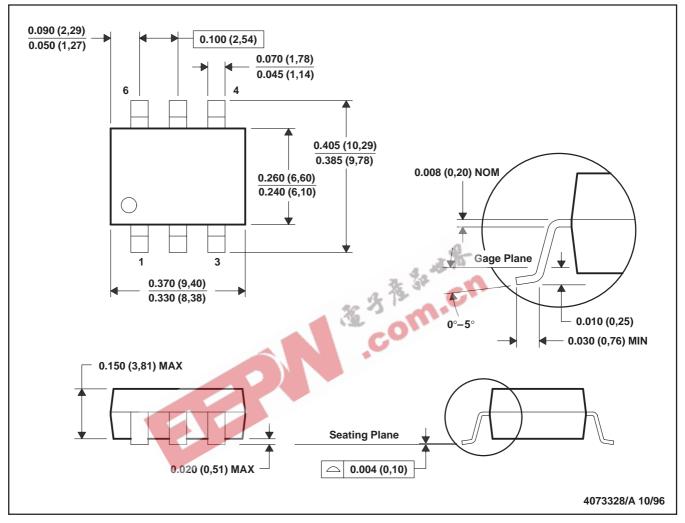
Figure 9. Plastic Dual-in-Line Package



#### **MECHANICAL DATA**

### DCJ (R-PDSO-G6)

## PLASTIC DUAL SMALL-OUTLINE OPTOCOUPLER



NOTES: A. All linear dimensions are in inches (millimeters)

B. This drawing is subject to change without notice.

C. Terminal 1 identified by index dot.

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